



US00D866533S

(12) **United States Design Patent**
Chong

(10) **Patent No.:** **US D866,533 S**

(45) **Date of Patent:** **** Nov. 12, 2019**

(54) **HEADPHONE STAND**

(71) Applicant: **RAZER (ASIA-PACIFIC) PTE. LTD.**,
Singapore (SG)

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Singapore (SG)

(**) Term: **15 Years**

(21) Appl. No.: **29/613,207**

(22) Filed: **Aug. 8, 2017**

(51) **LOC (12) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/224**

(58) **Field of Classification Search**
USPC D14/224-229; D16/244; D17/99;
D6/672, 681, 682; 248/125.1, 166, 185.1;
(Continued)

(56) **References Cited**

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Primary Examiner — Katie Jane Stofko

(74) *Attorney, Agent, or Firm* — Polsinelli PC

(57) **CLAIM**

I claim the ornamental design for a headphone stand, as shown and described.

DESCRIPTION

FIG. 1 is a top, perspective view of a first embodiment of a headphone stand, showing my new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;

FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof;
FIG. 7 is a bottom plan view thereof, wherein oblique line shading indicates a transparent surface;
FIG. 8 is a bottom, perspective view thereof, wherein oblique line shading indicates a transparent surface; and
FIG. 9 is an exploded, top, perspective view thereof, showing the top portion of the headphone stand exploded from the base portion.

FIG. 10 is a top, perspective view of a second embodiment of the headphone stand, the second embodiment being the same as the first embodiment; except that broken lines are used to illustrate unclaimed portions of the headphone stand.

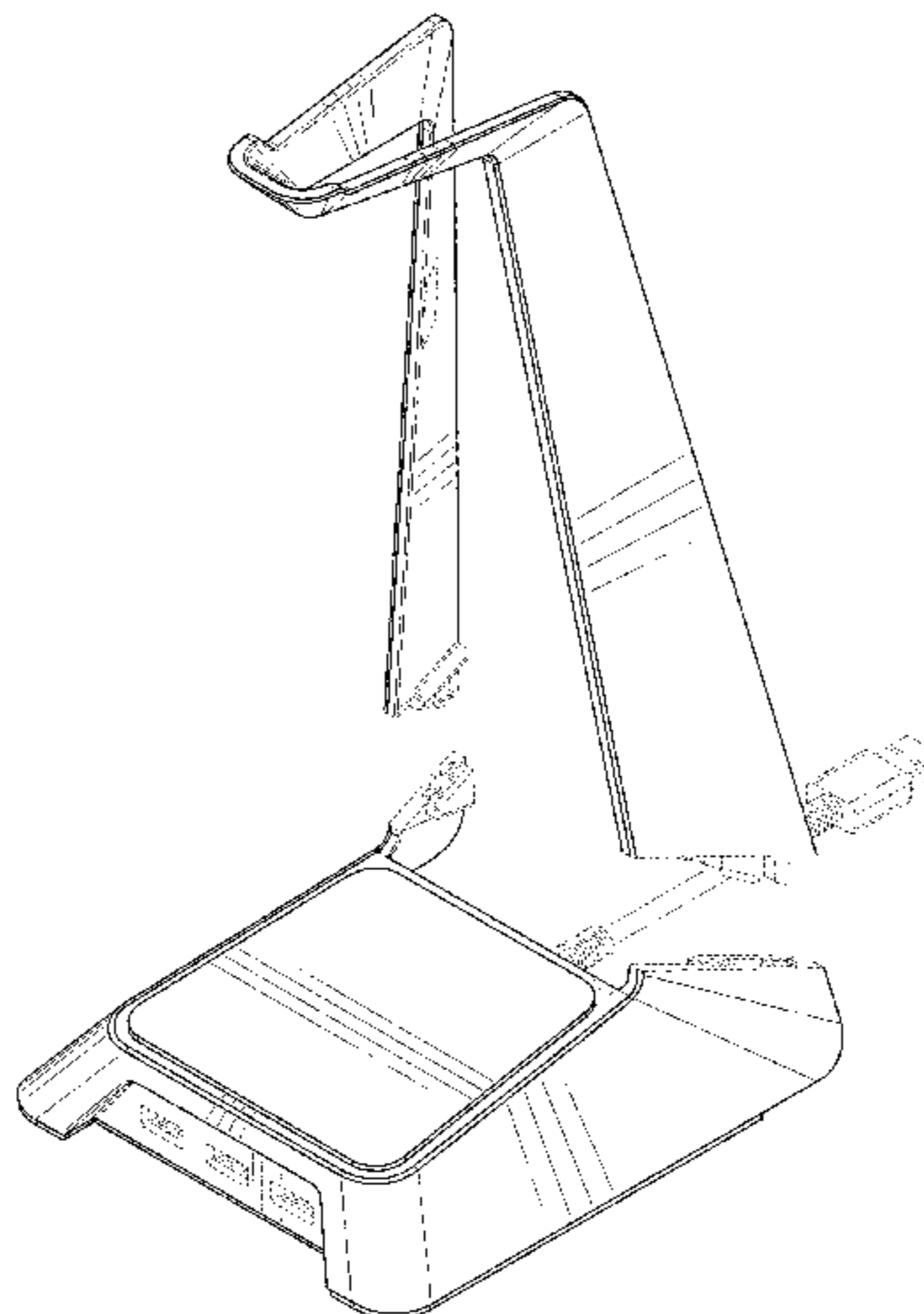
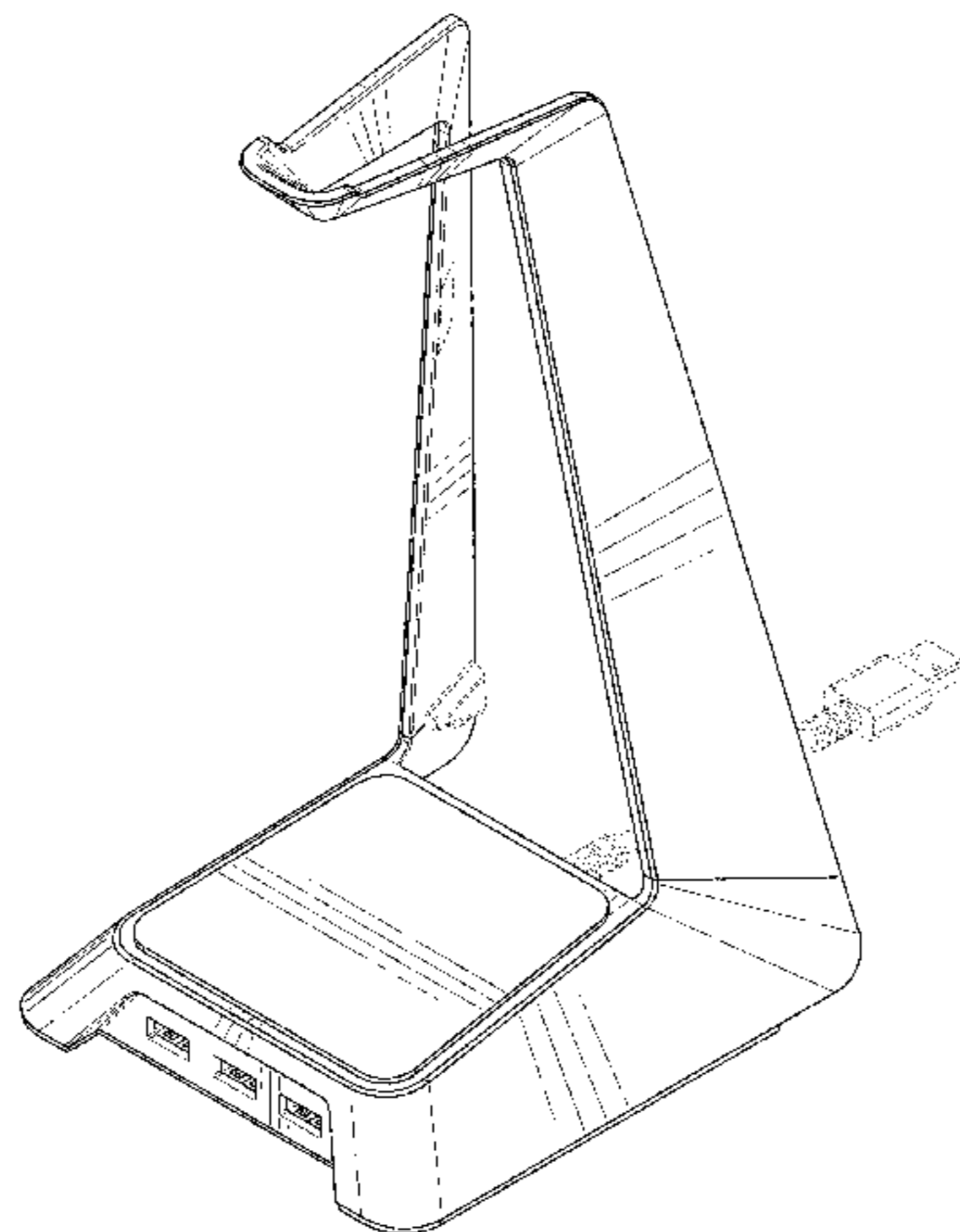
FIG. 11 is a front elevational view thereof;
FIG. 12 is a rear elevational view thereof;
FIG. 13 is a left side elevational view thereof;
FIG. 14 is a right side elevational view thereof;
FIG. 15 is a top plan view thereof;
FIG. 16 is a bottom plan view thereof, wherein oblique line shading indicates a transparent surface;

FIG. 17 is a bottom, perspective view thereof, wherein oblique line shading indicates a transparent surface; and
FIG. 18 is an exploded, top, perspective view thereof, showing top portion of the headphone stand exploded from the base portion.

FIG. 19 is an exploded, top, perspective view of a third embodiment of the headphone stand, the third embodiment being the same as the second embodiment; except that the design is exploded.

FIG. 20 is an exploded, front elevational view thereof;
FIG. 21 is an exploded, rear elevational view thereof;
FIG. 22 is an exploded, left side elevational view thereof;
FIG. 23 is an exploded, right side elevational view thereof;
FIG. 24 is an exploded, top plan view thereof;
FIG. 25 is an exploded, bottom plan view thereof, wherein oblique line shading indicates a transparent surface; and,
FIG. 26 is an exploded, bottom, perspective view thereof, wherein oblique line shading indicates a transparent surface.
The broken lines depict portions of the headphone stand which form no part of the claimed design.

1 Claim, 26 Drawing Sheets



(58) **Field of Classification Search**

USPC 381/355, 359, 361–363, 365, 366, 369,
381/375; 379/428.01, 428.04, 431,
379/433.03

CPC . H04R 25/00; H04R 1/02; H04R 5/02; H04R
9/08; F16M 11/38; F16M 13/00; F16M
11/00

See application file for complete search history.

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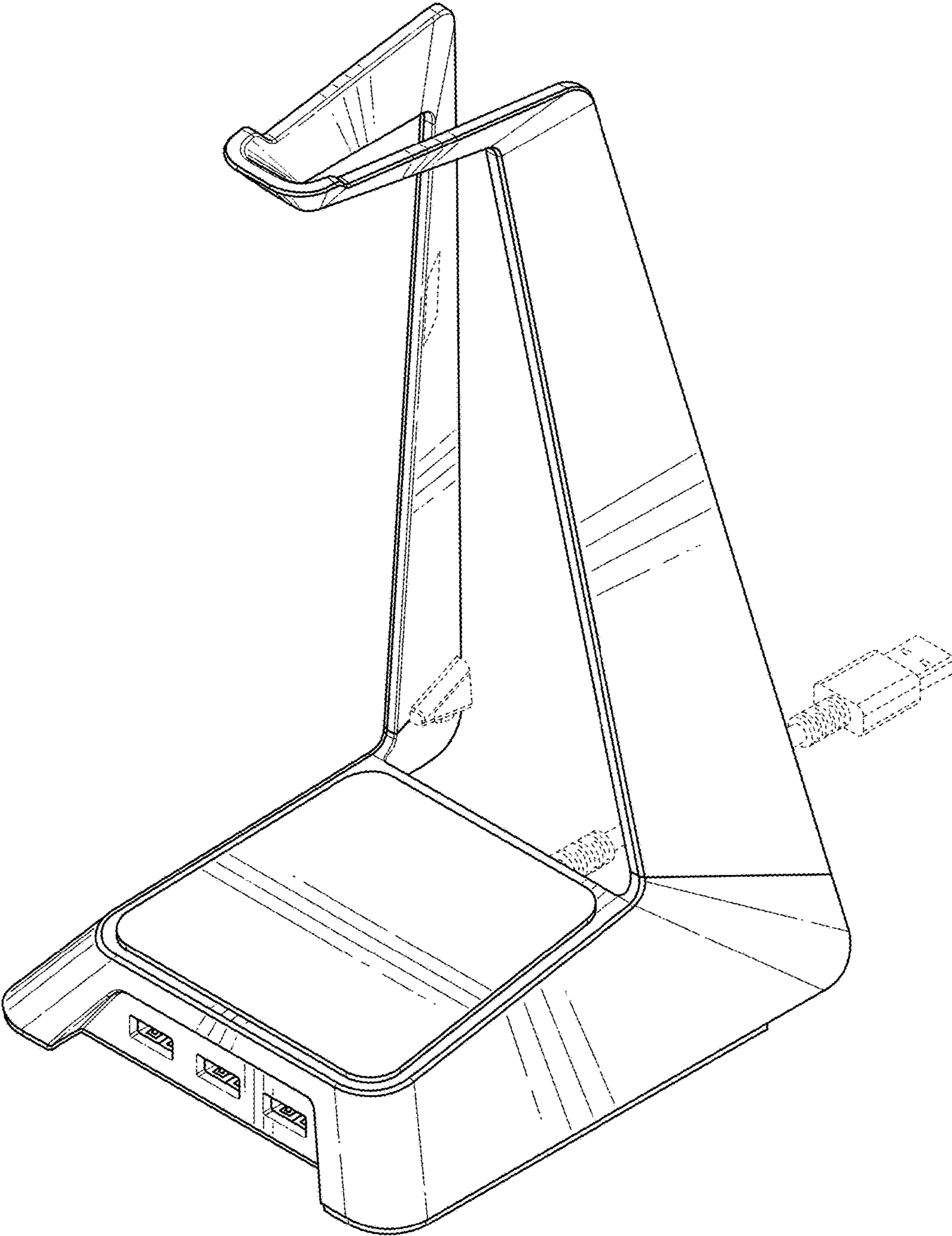


FIG. 1

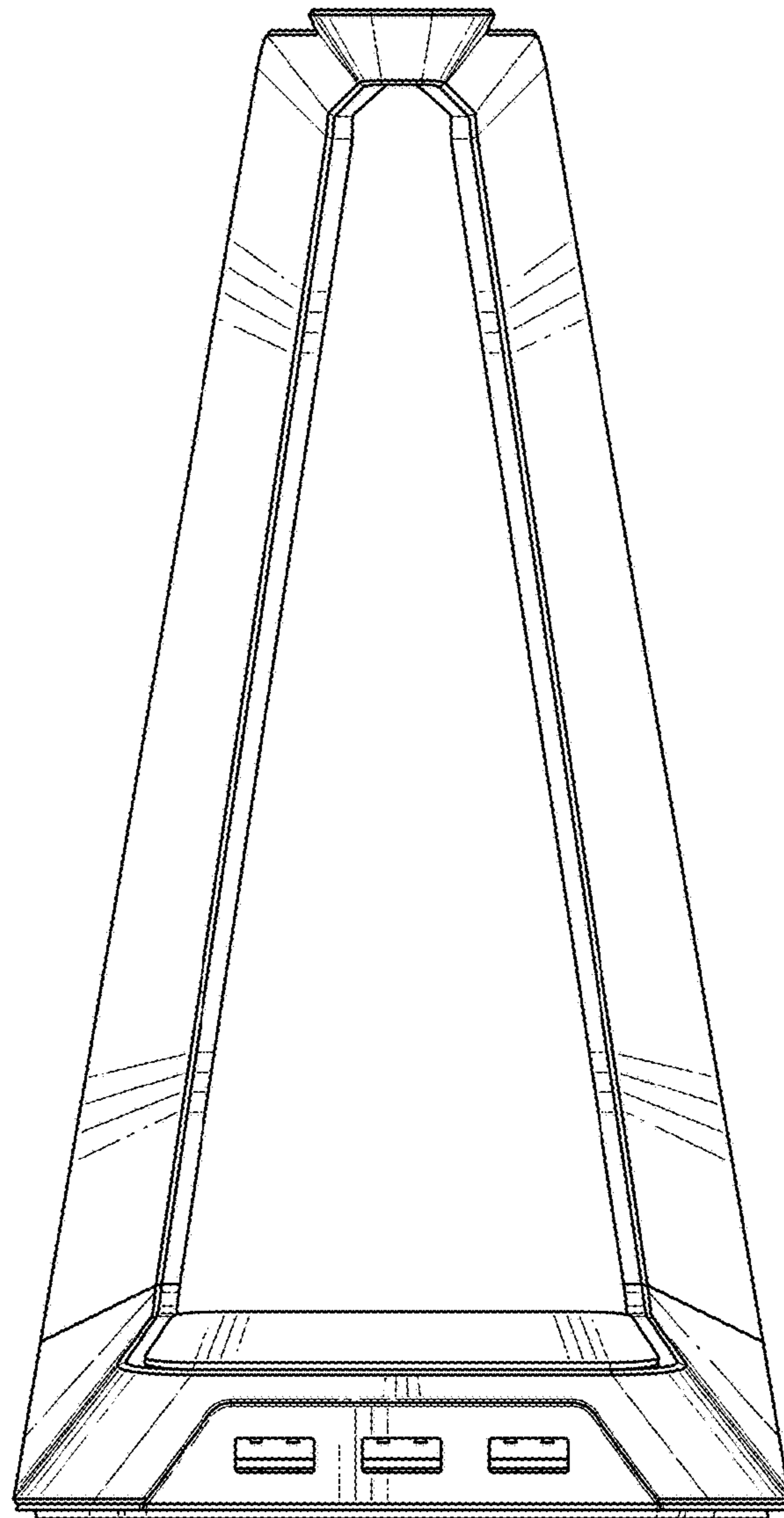


FIG. 2

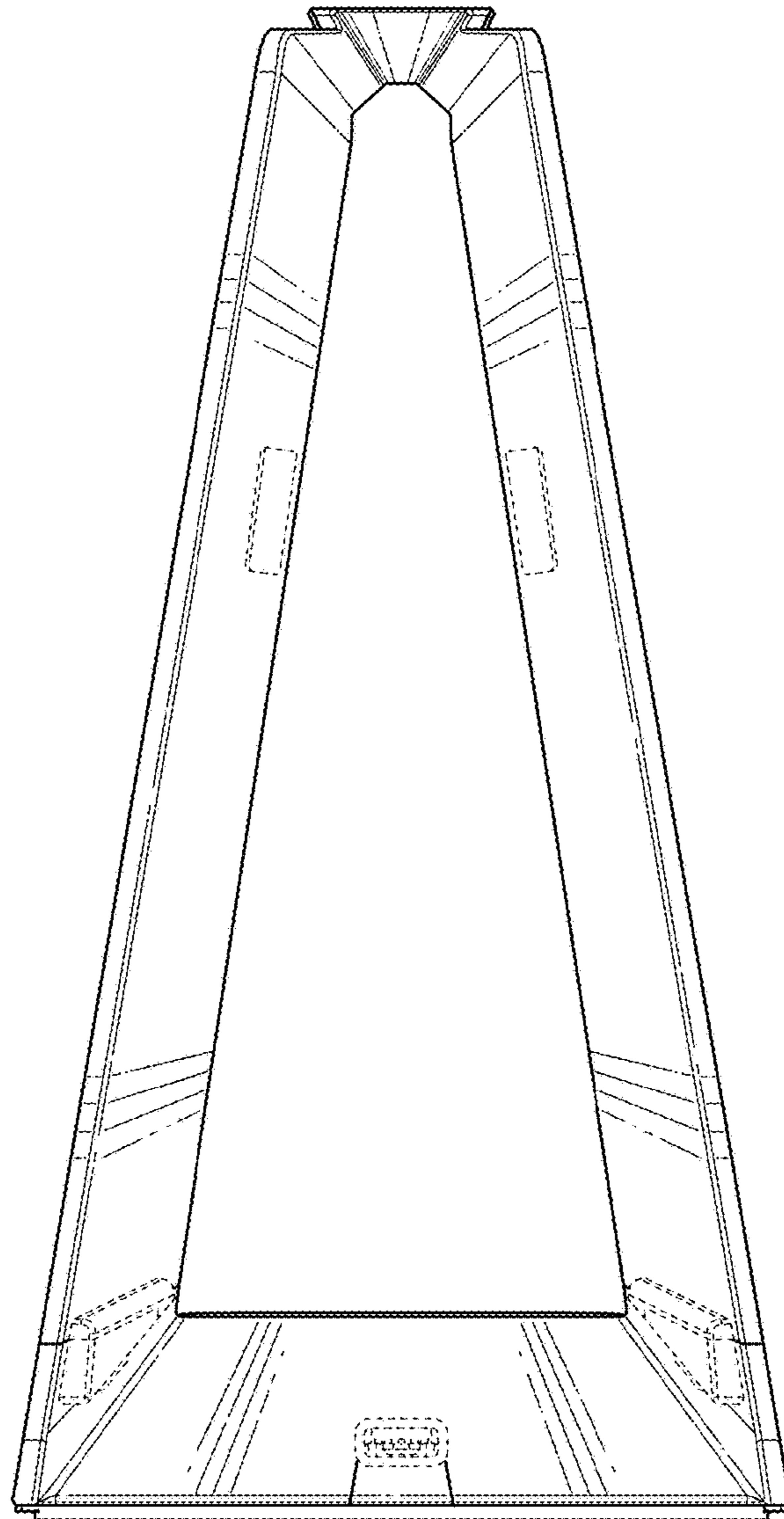


FIG. 3

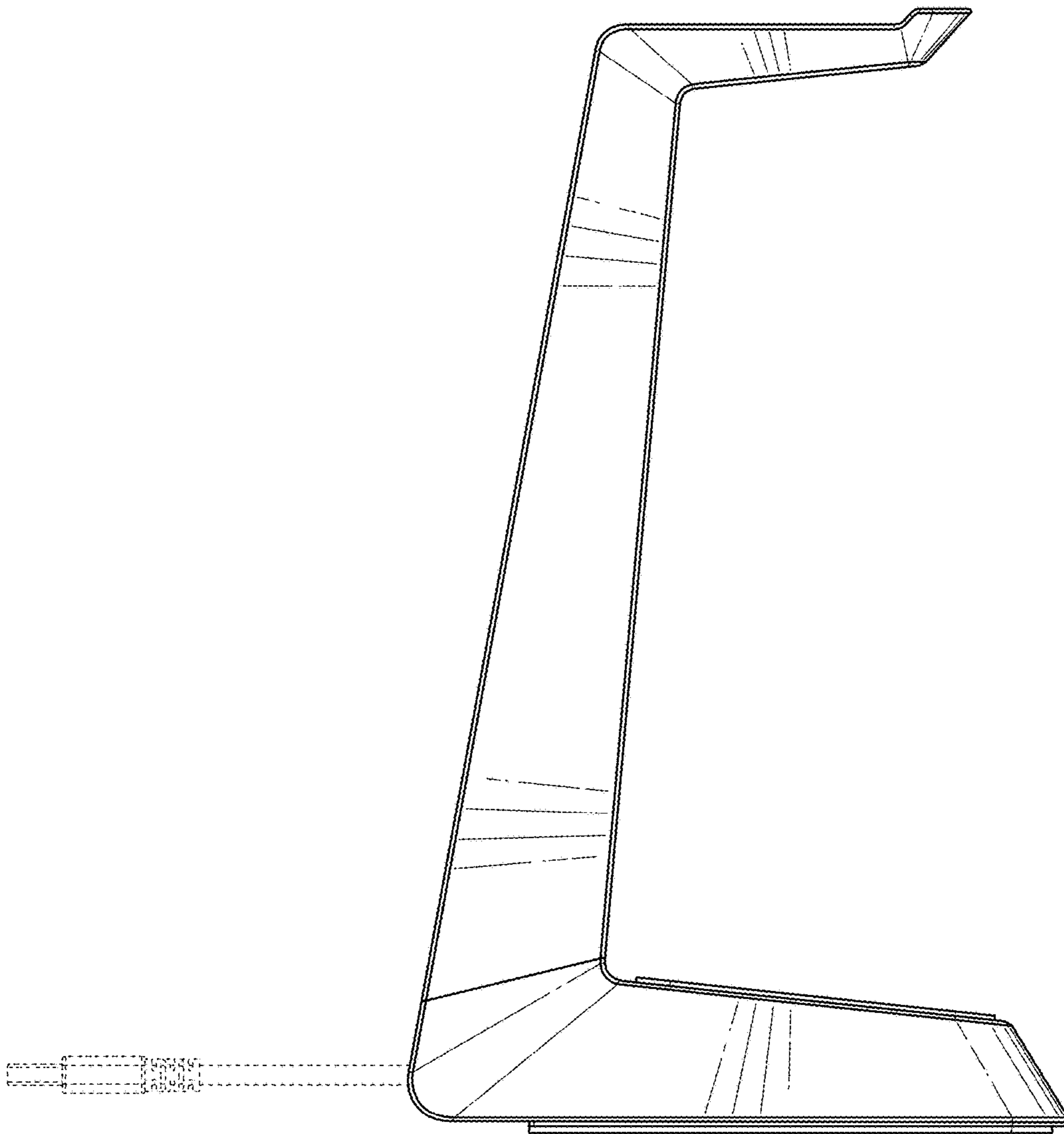


FIG. 4

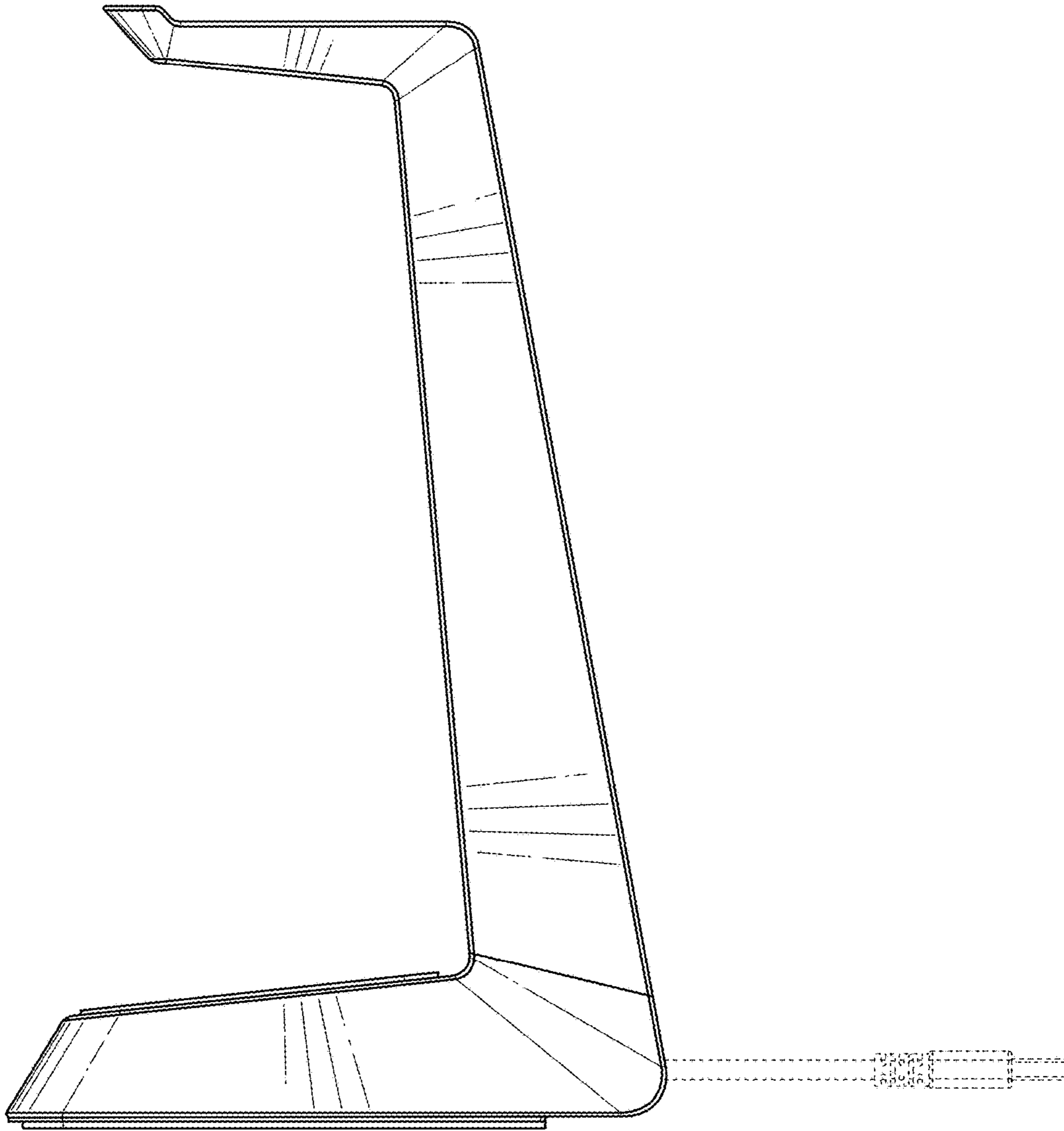


FIG. 5

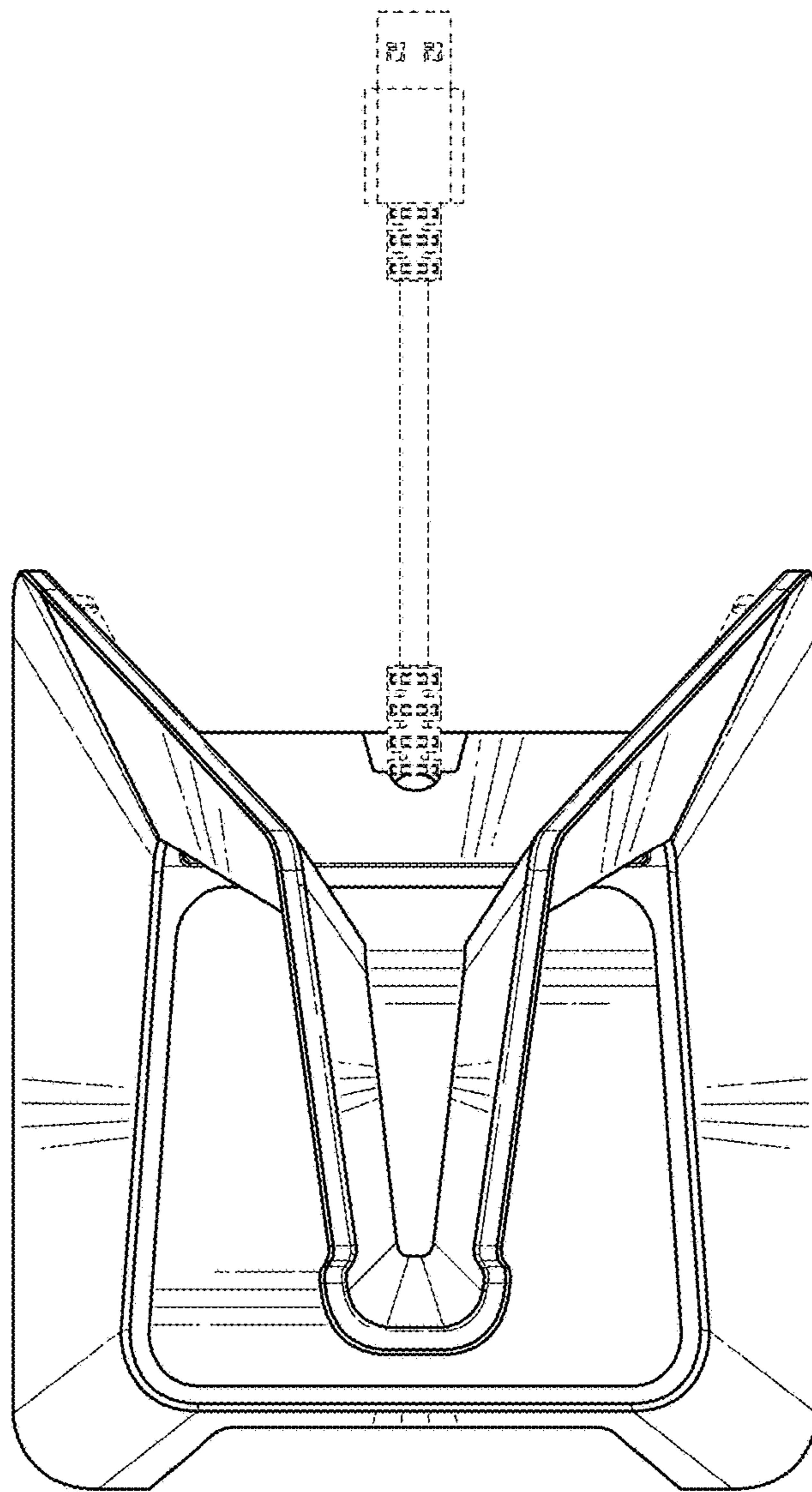


FIG. 6

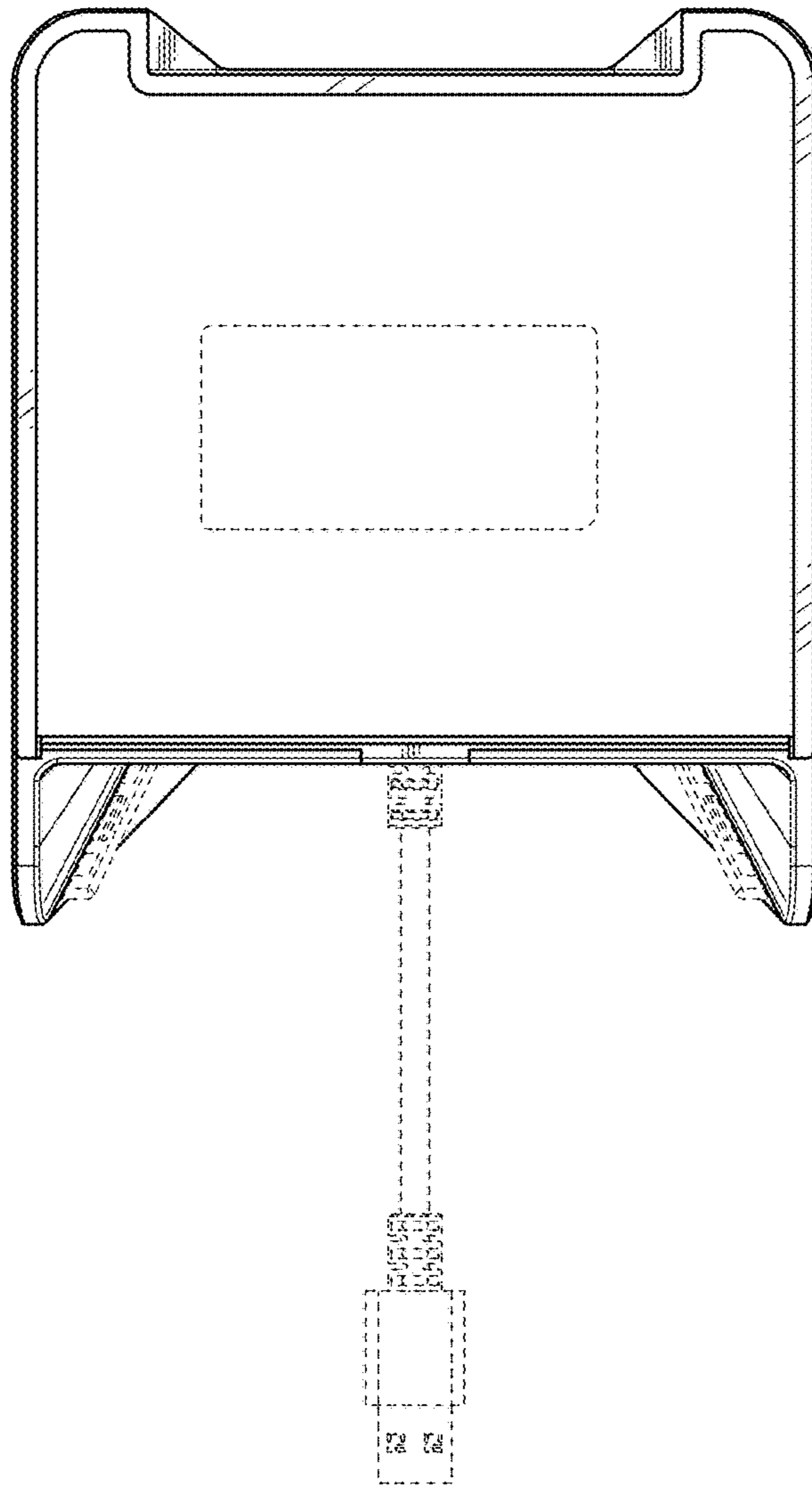


FIG. 7

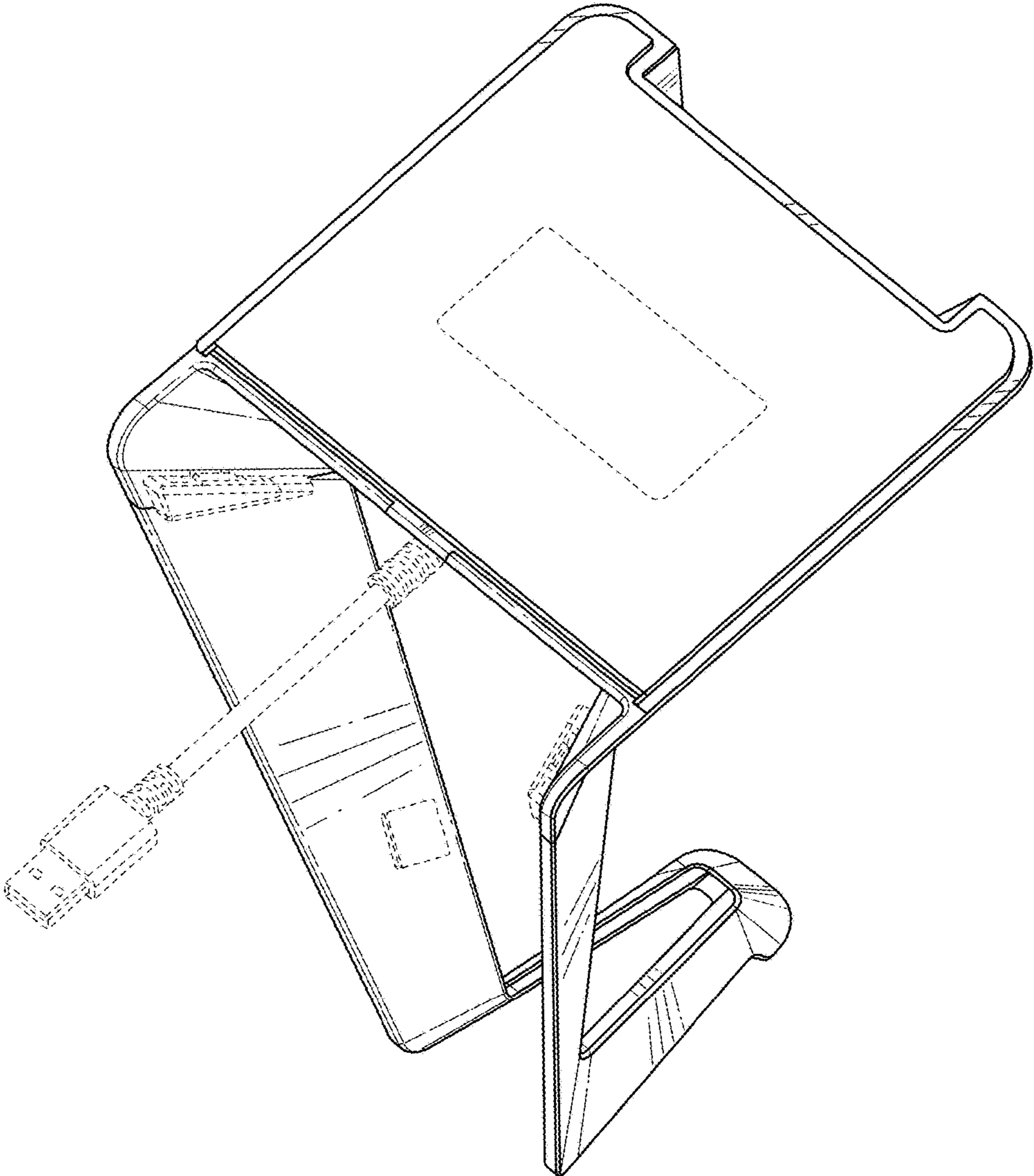


FIG. 8

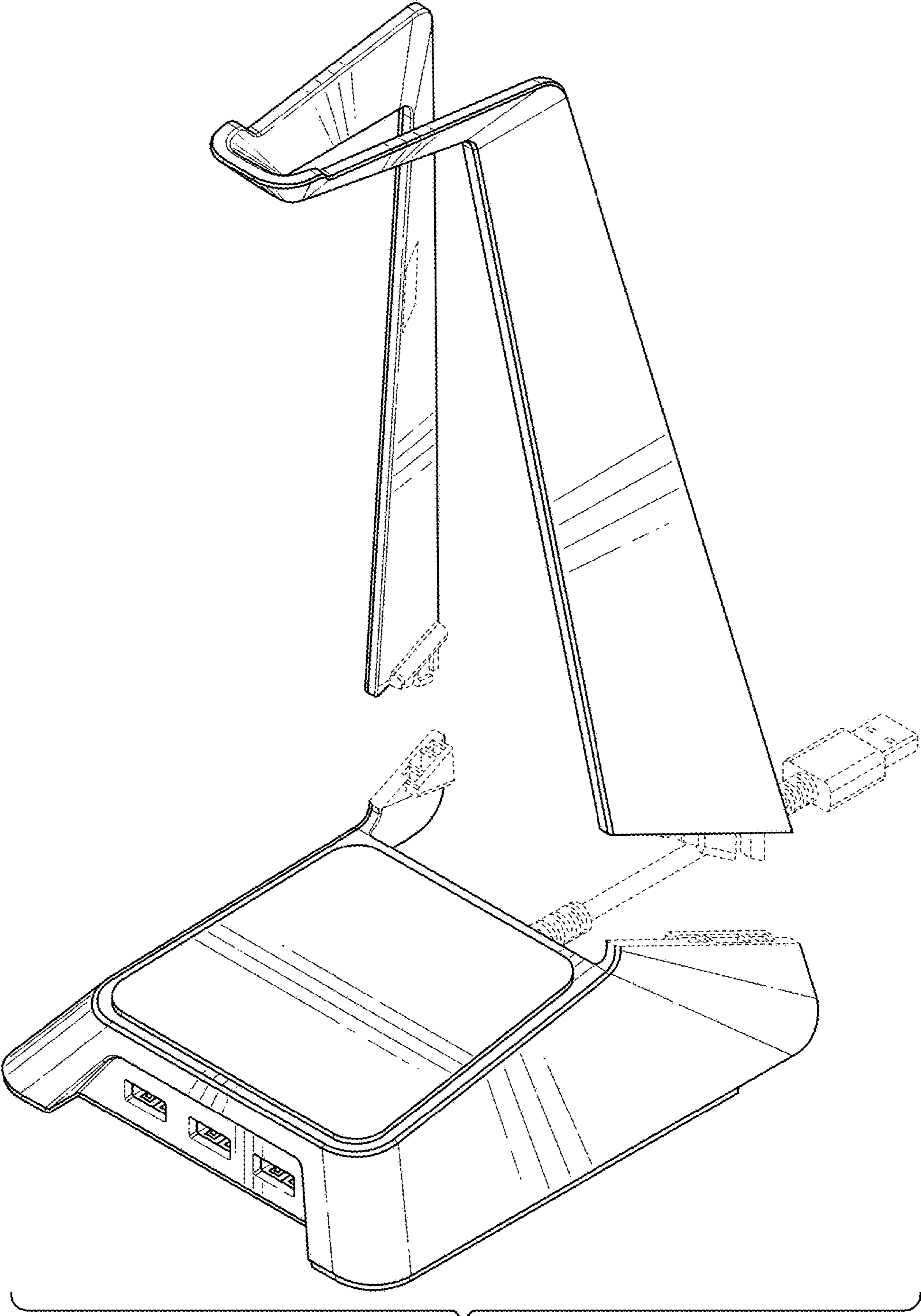


FIG. 9

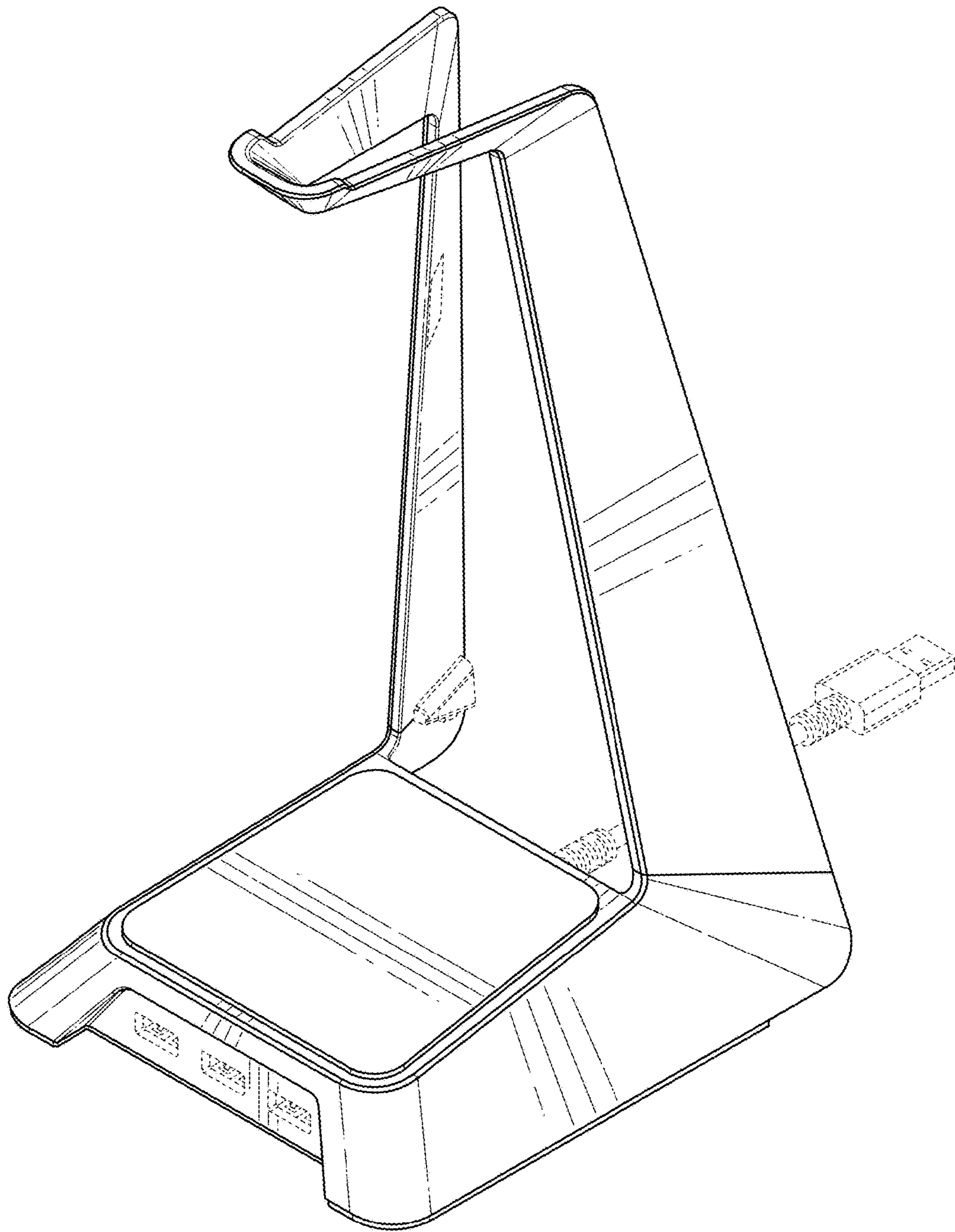


FIG. 10

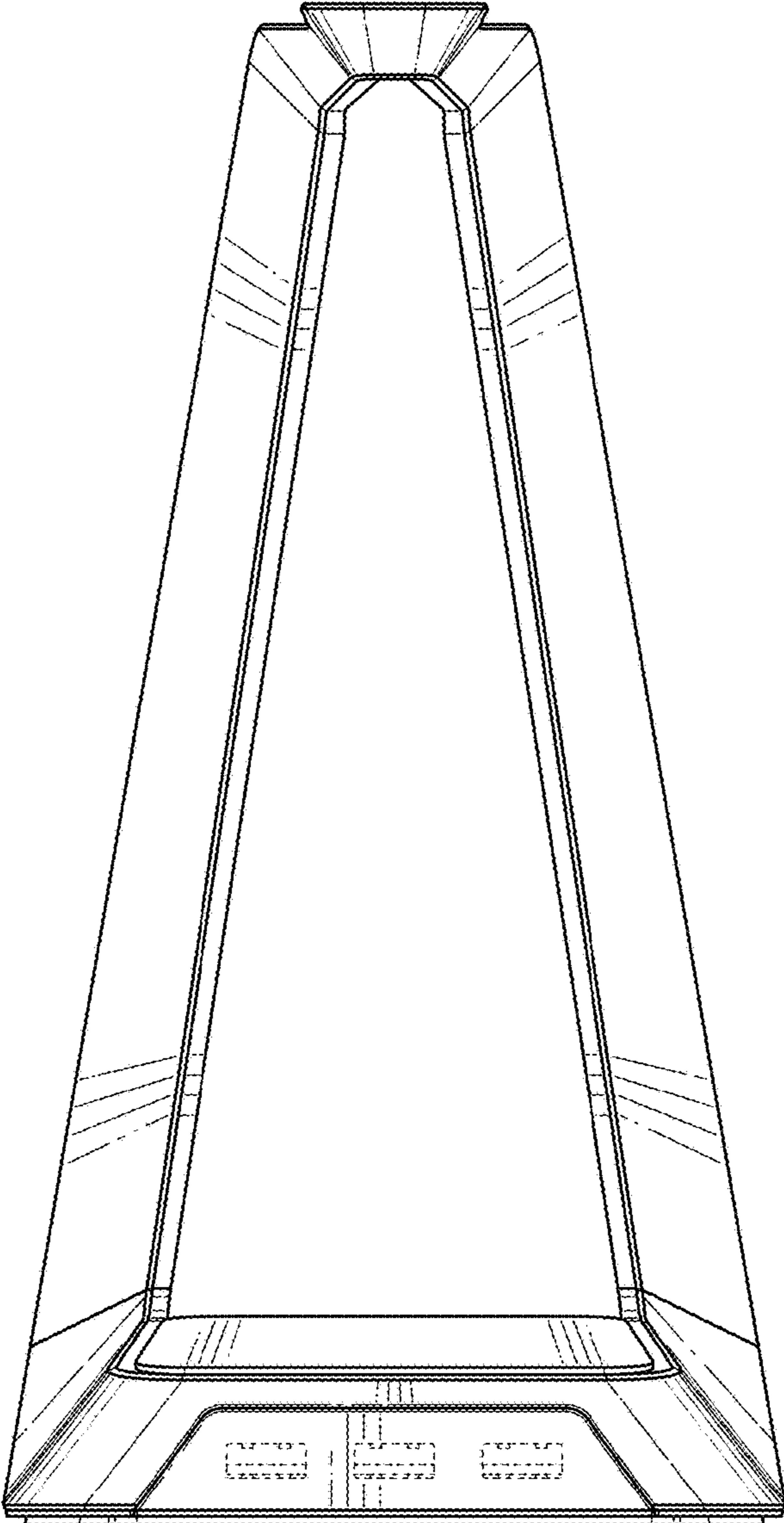


FIG. 11

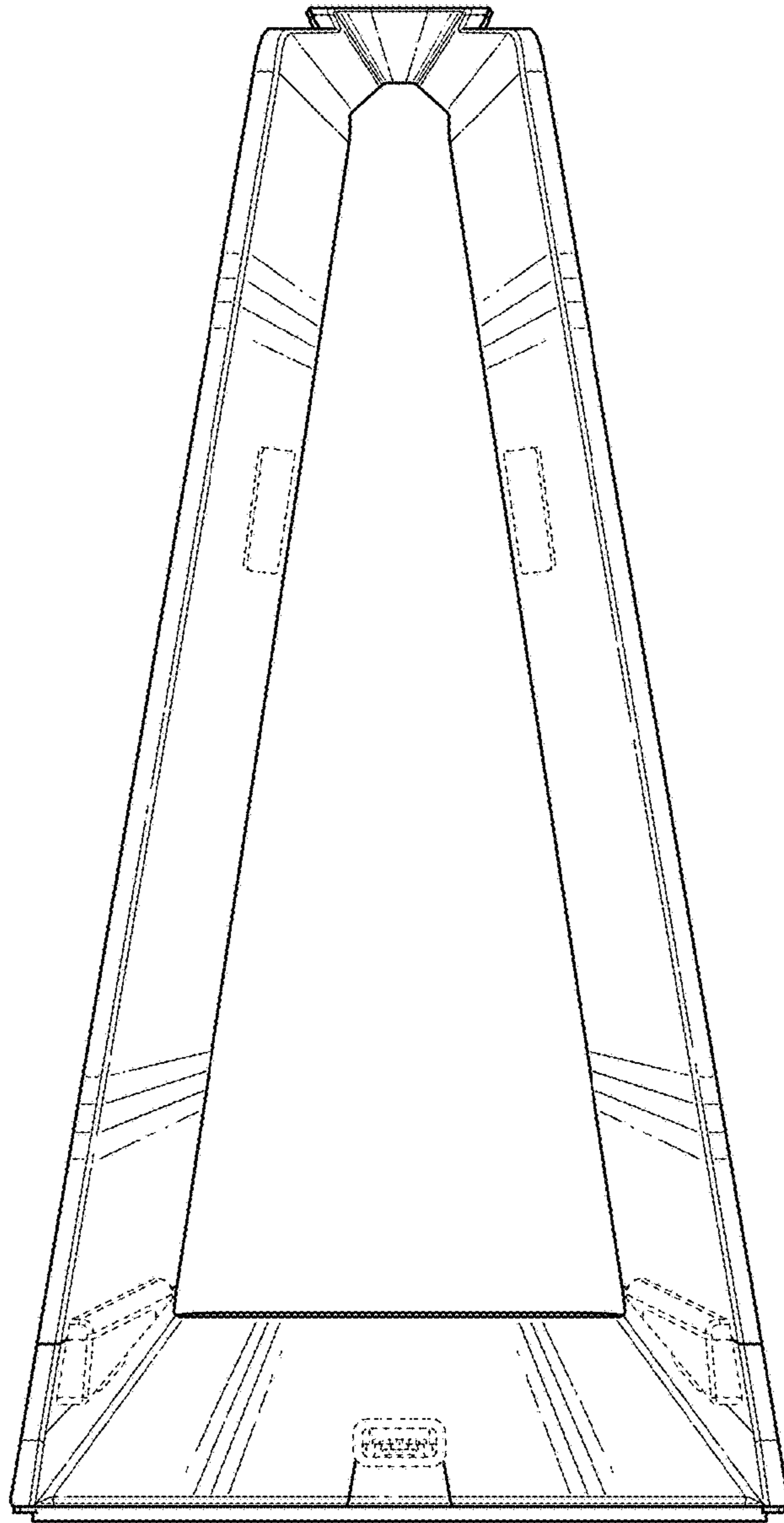


FIG. 12

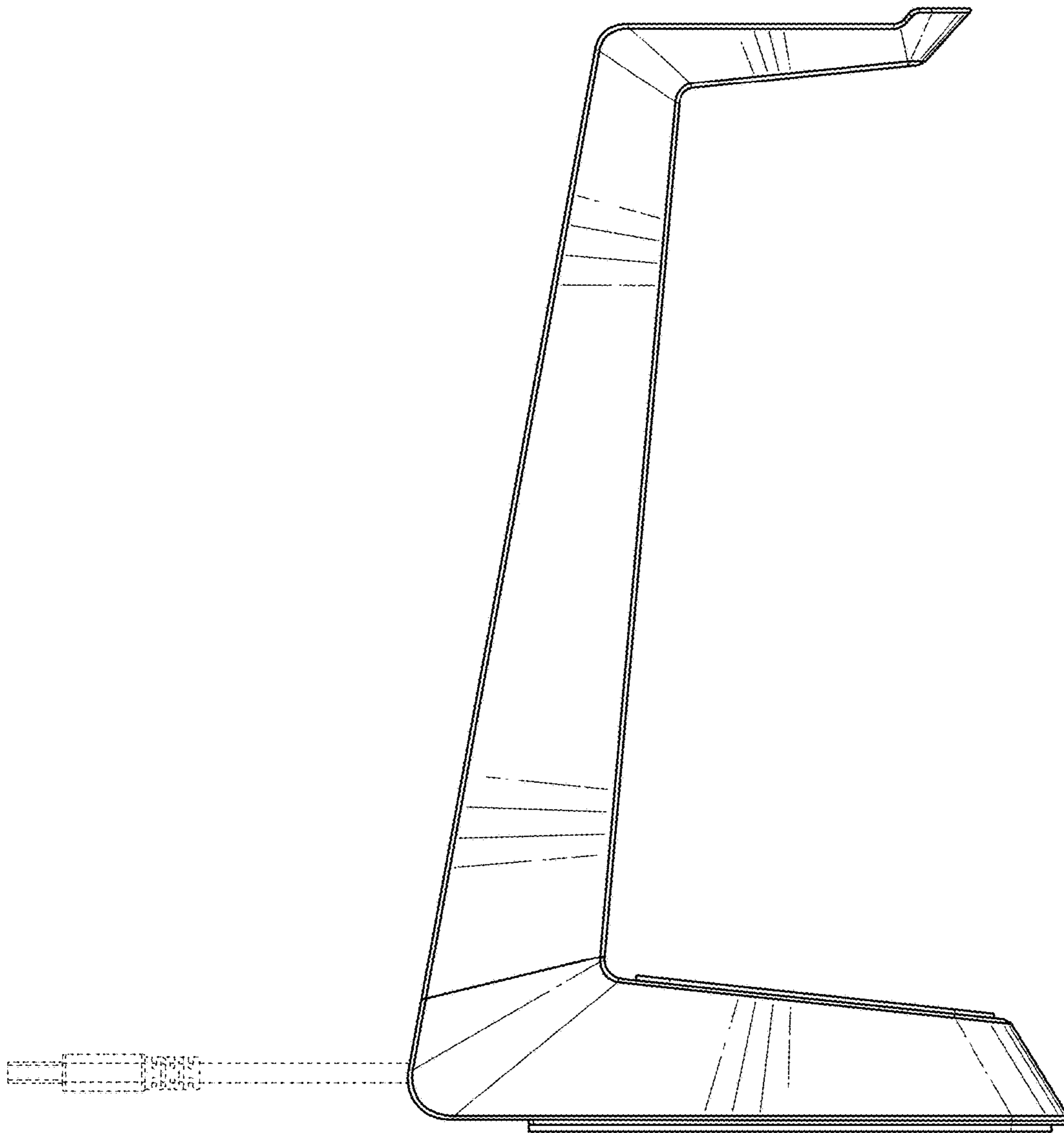


FIG. 13

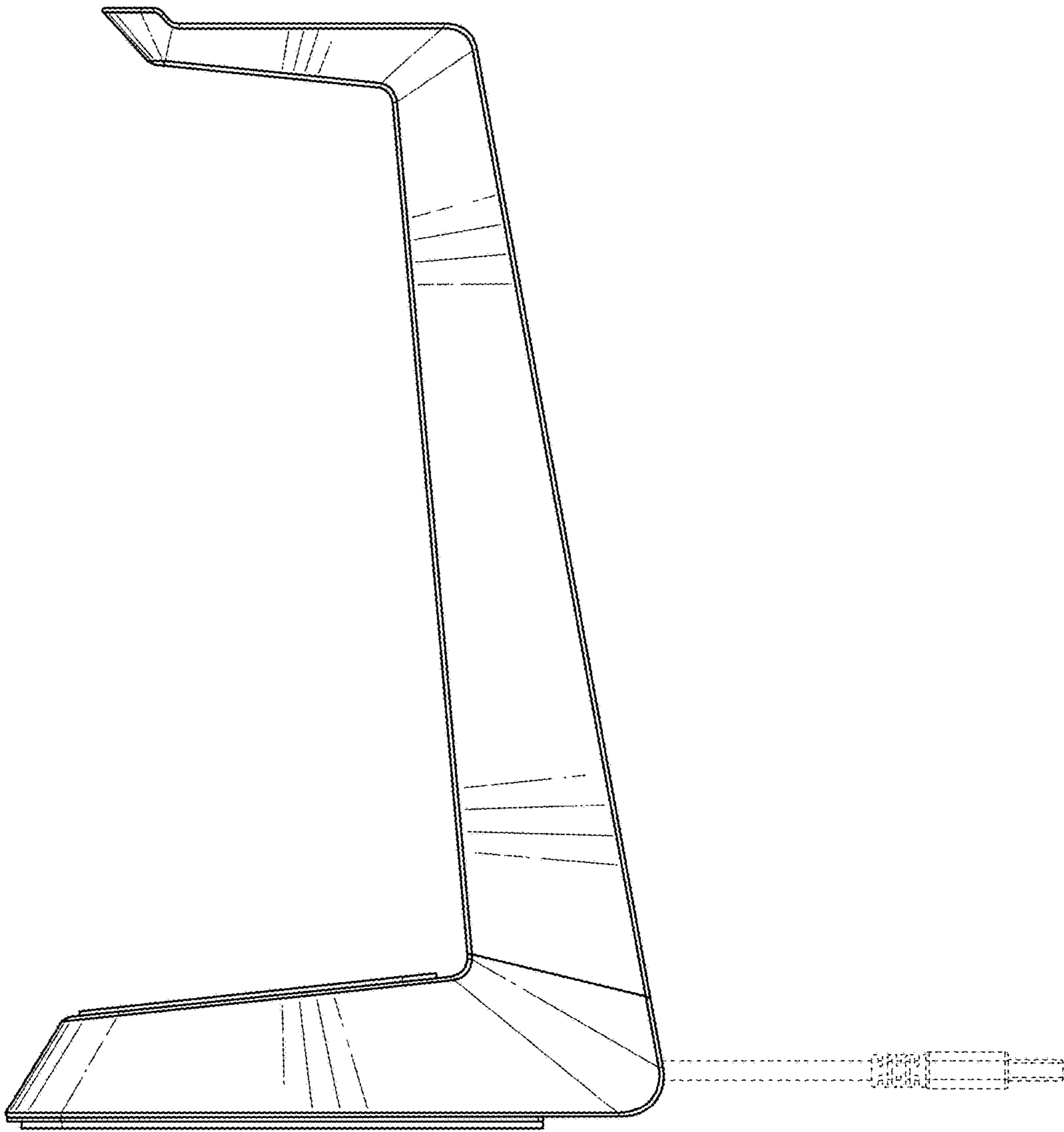


FIG. 14

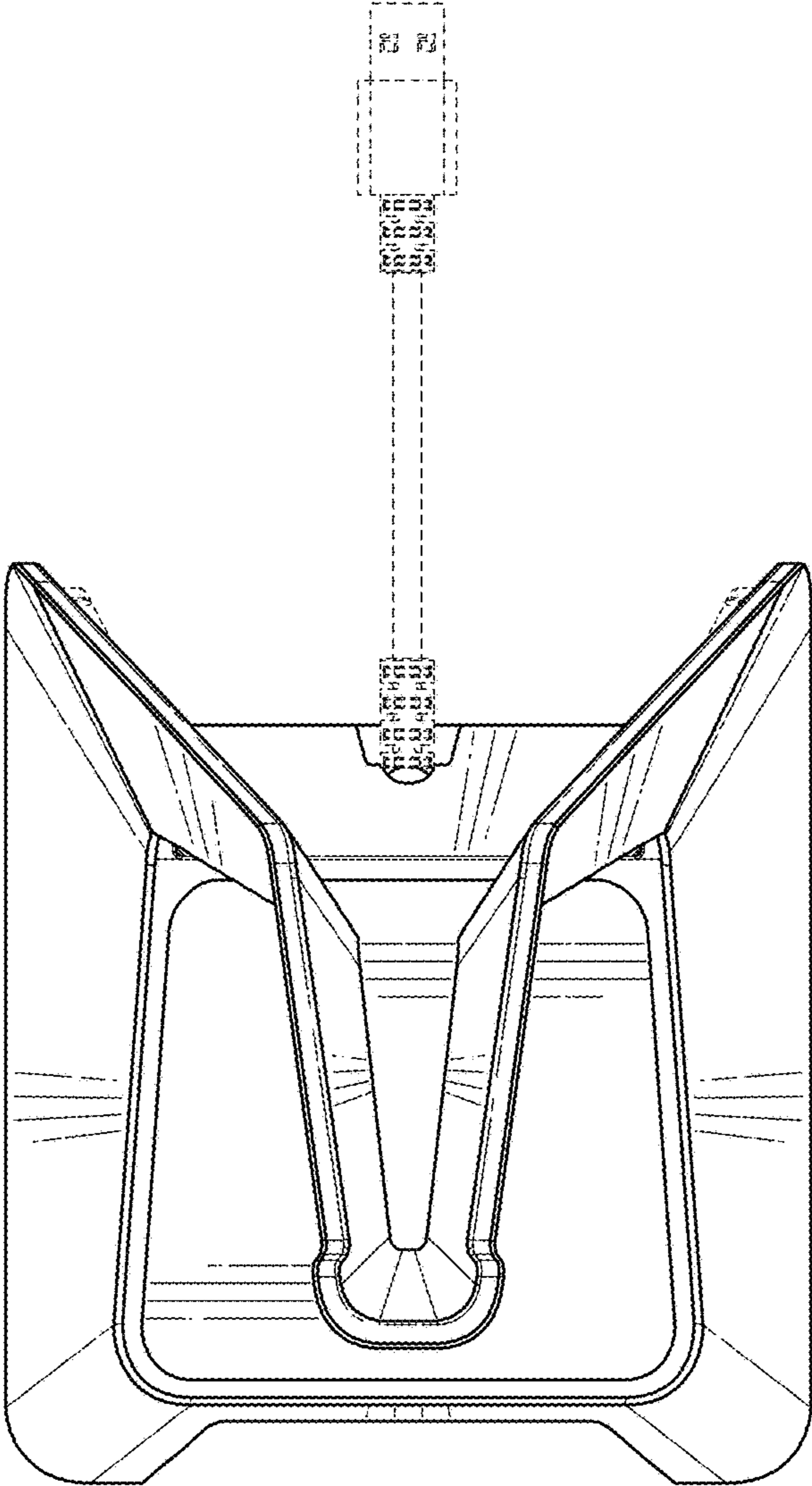


FIG. 15

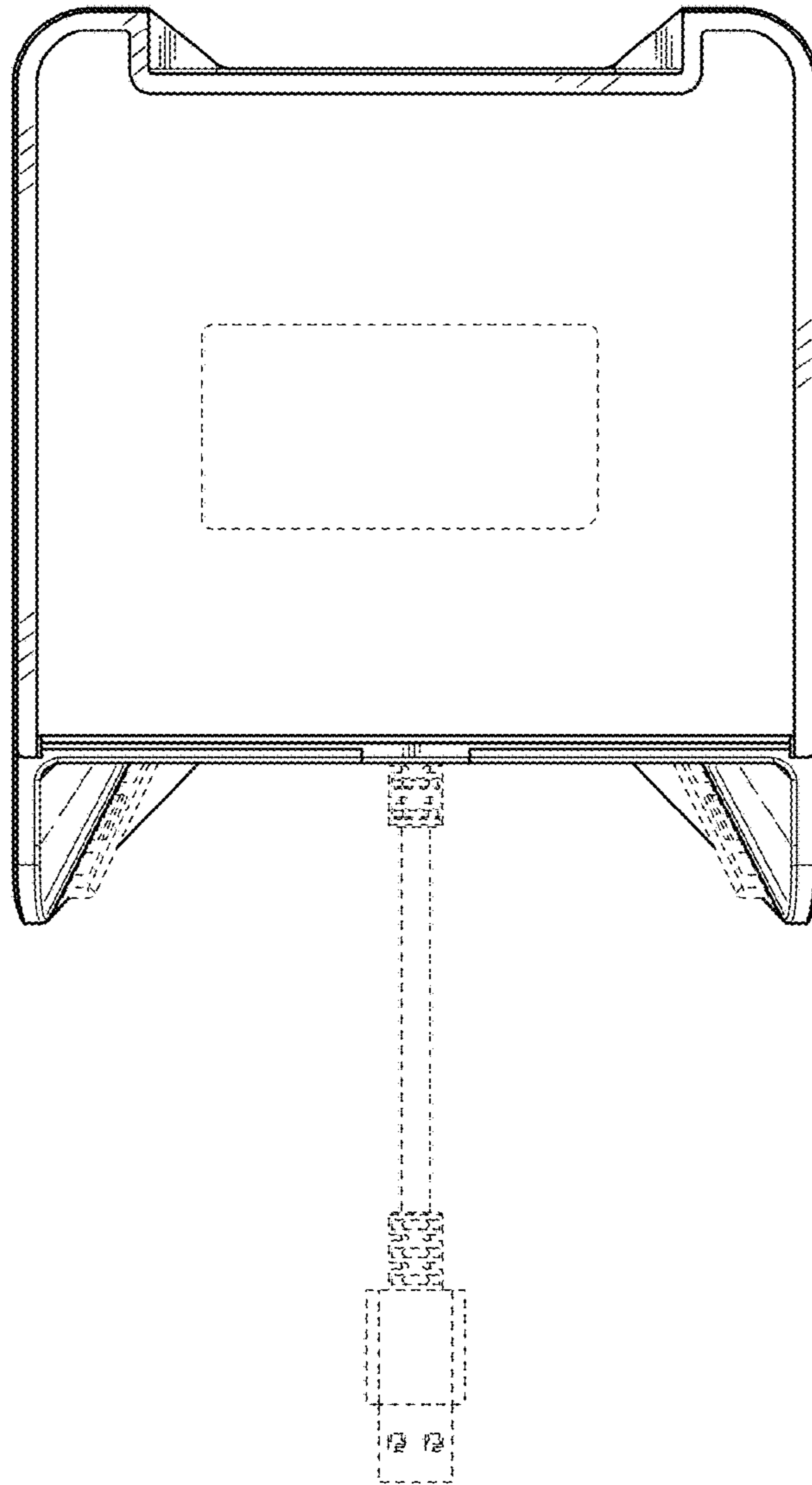


FIG. 16

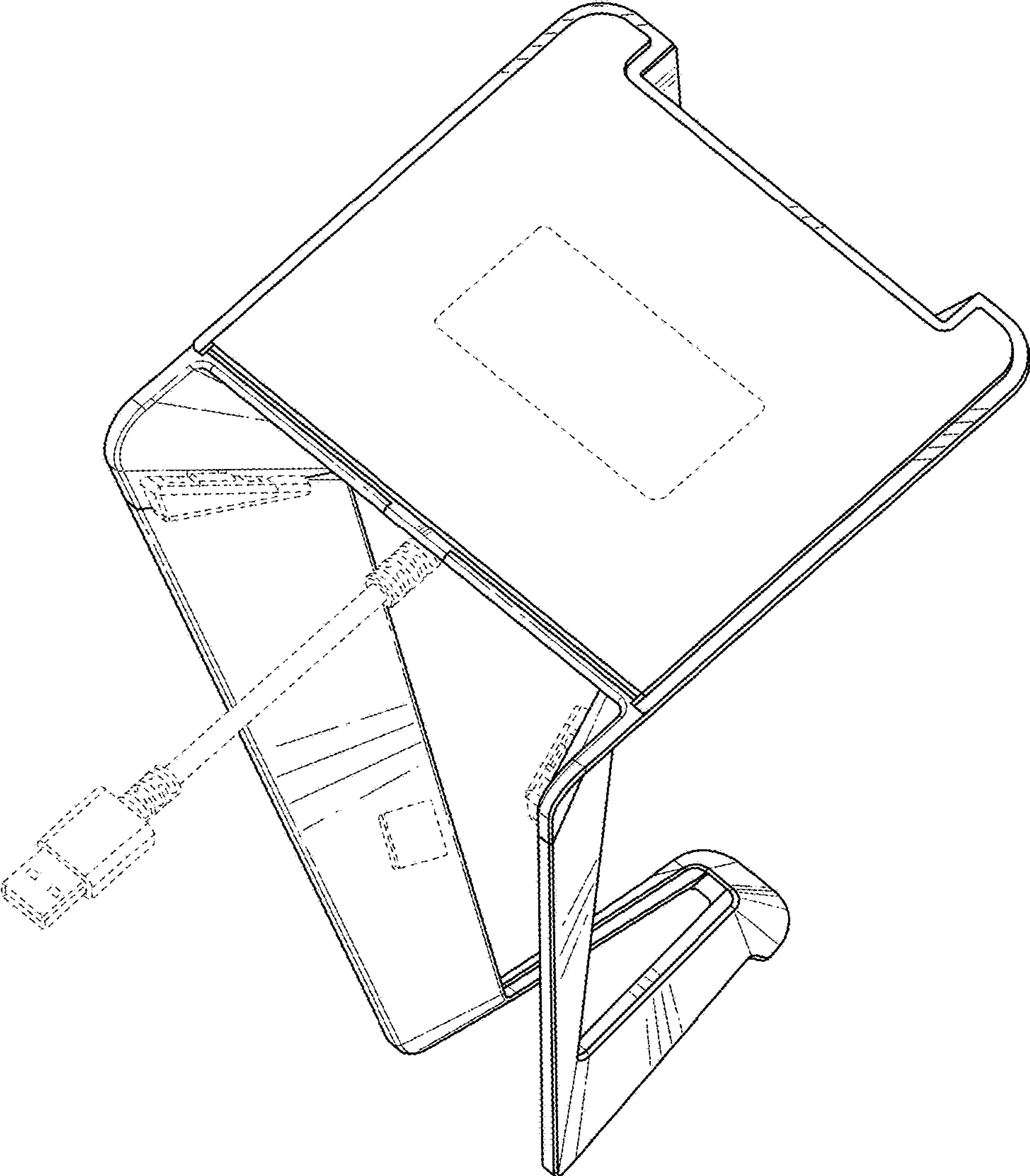


FIG. 17

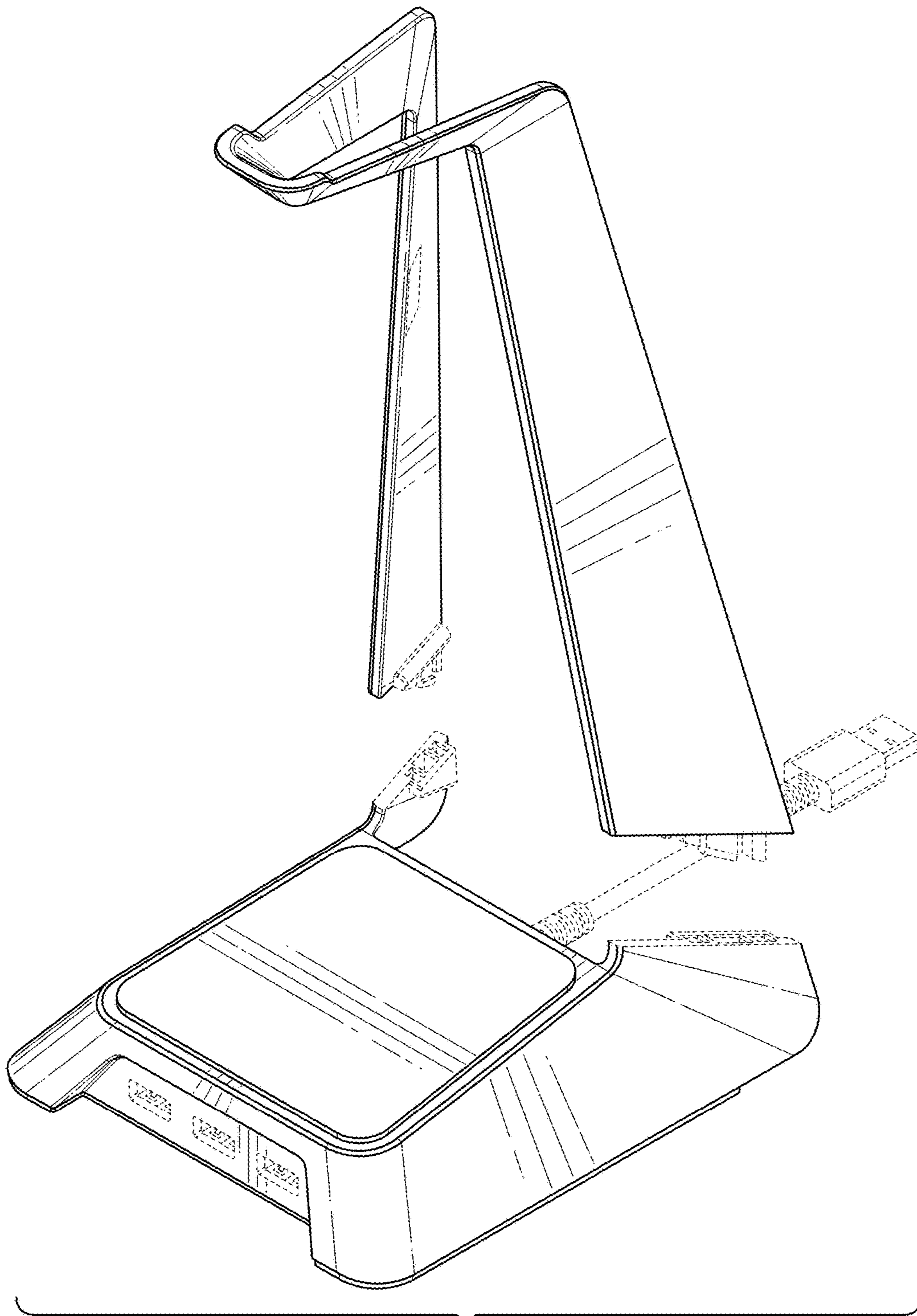


FIG. 18

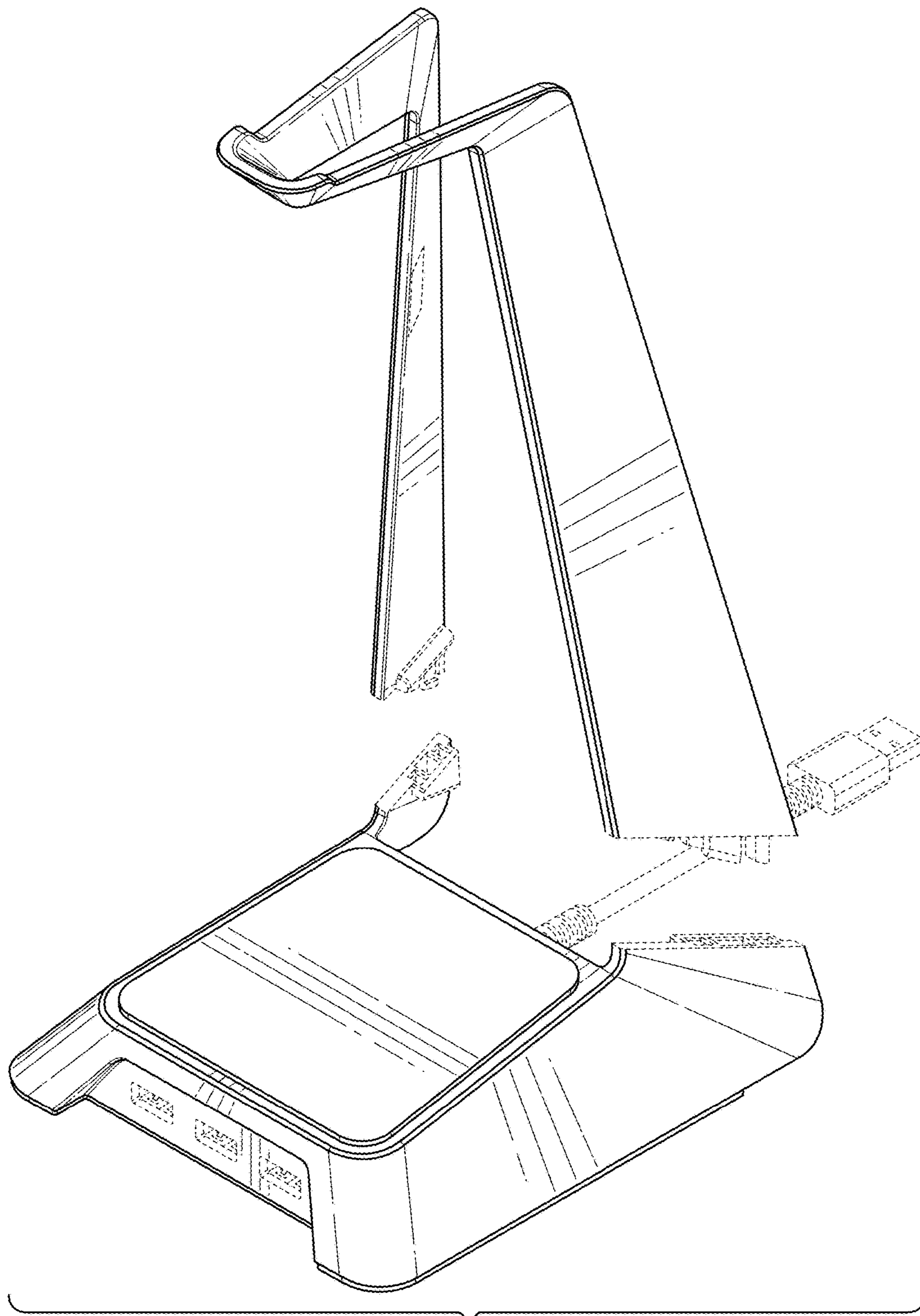


FIG. 19

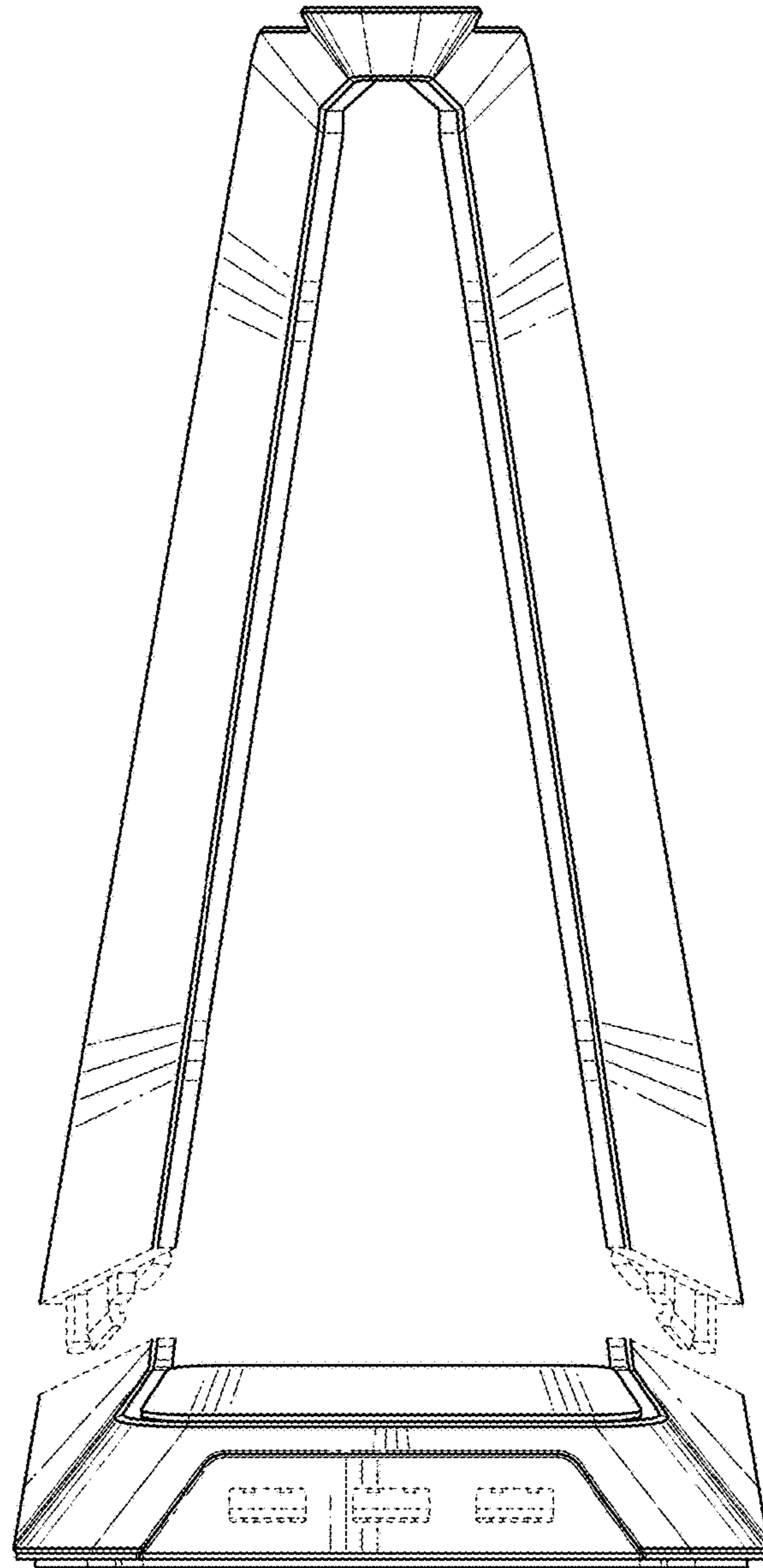


FIG. 20

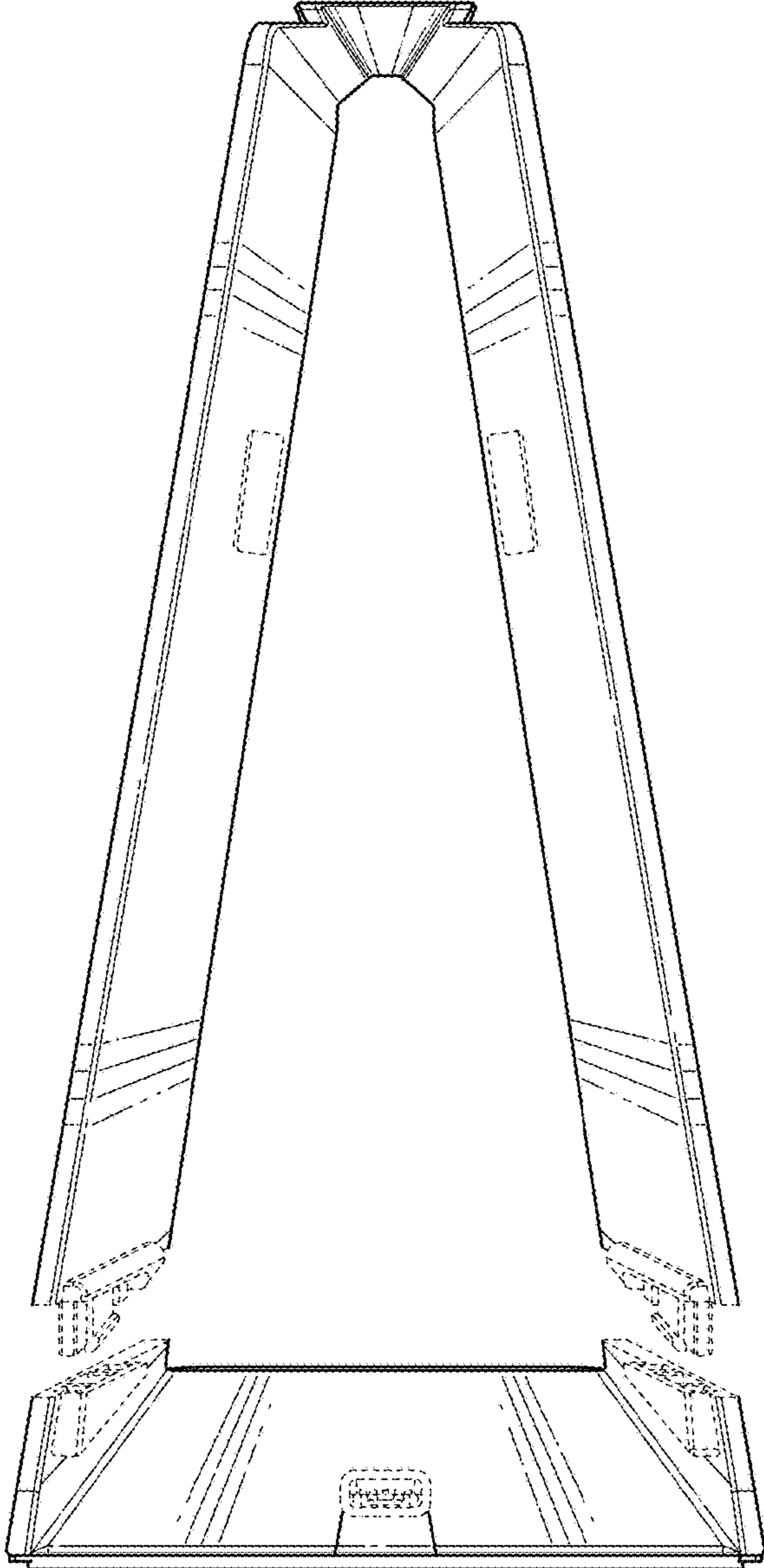


FIG. 21

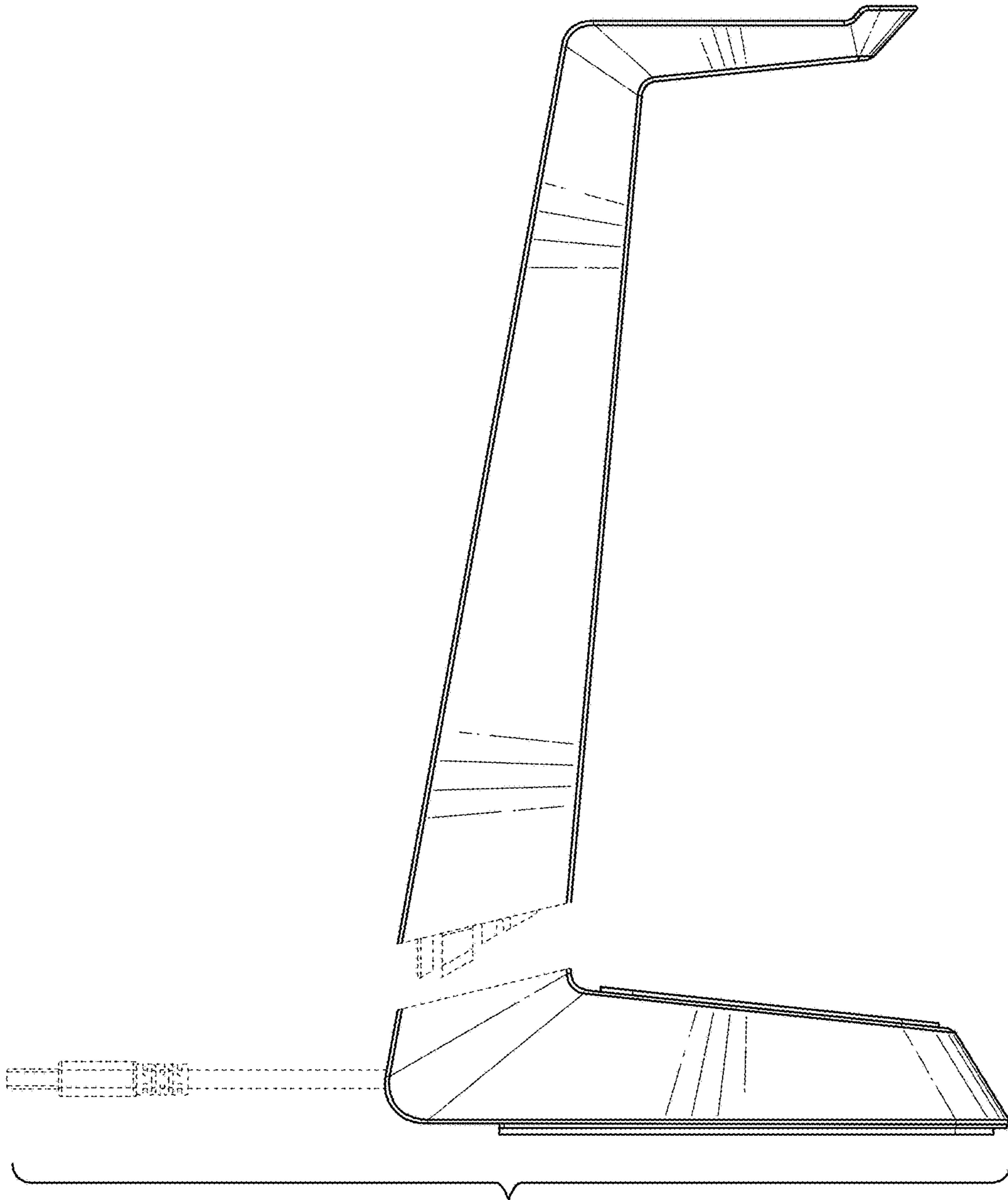


FIG. 22

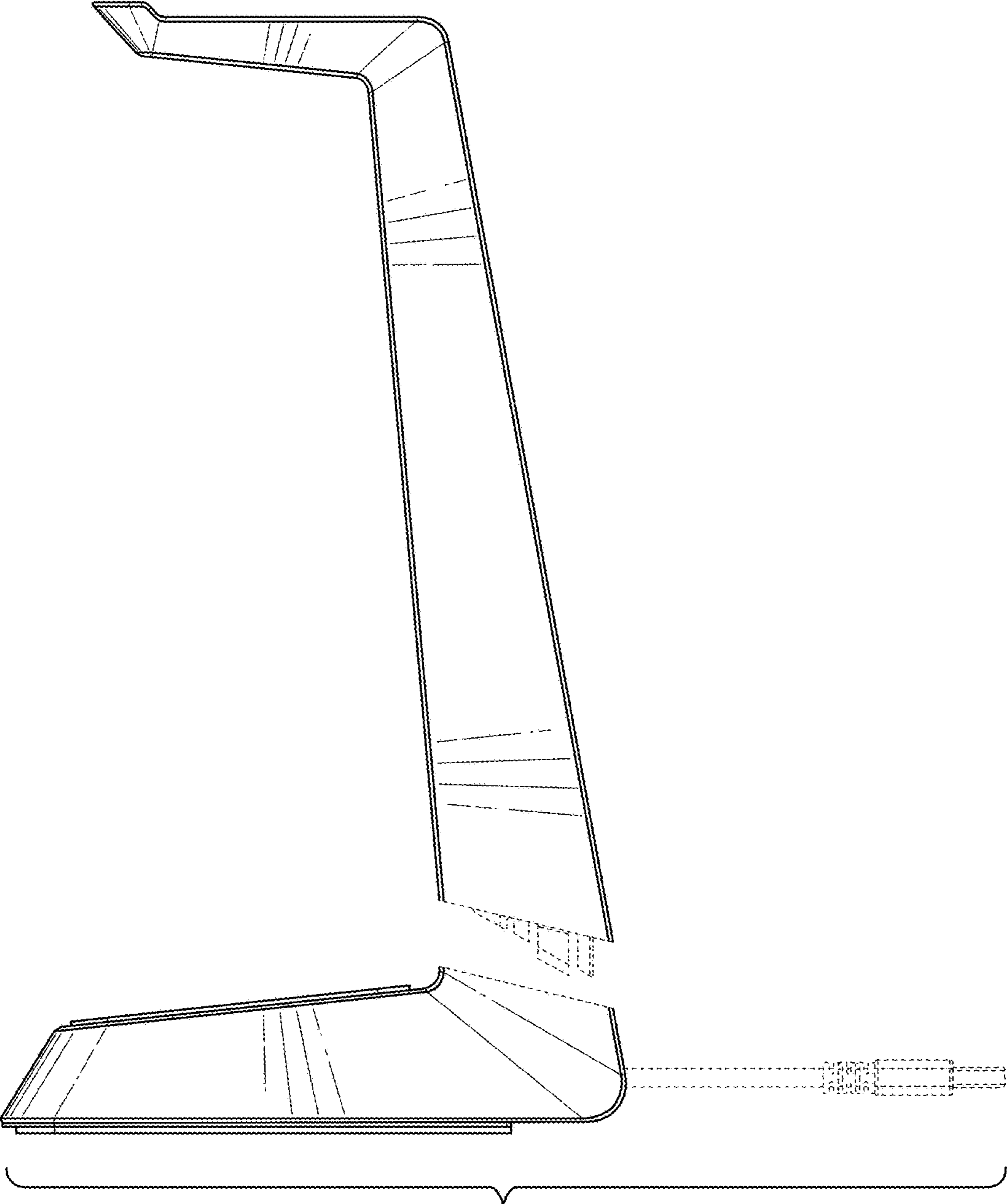


FIG. 23

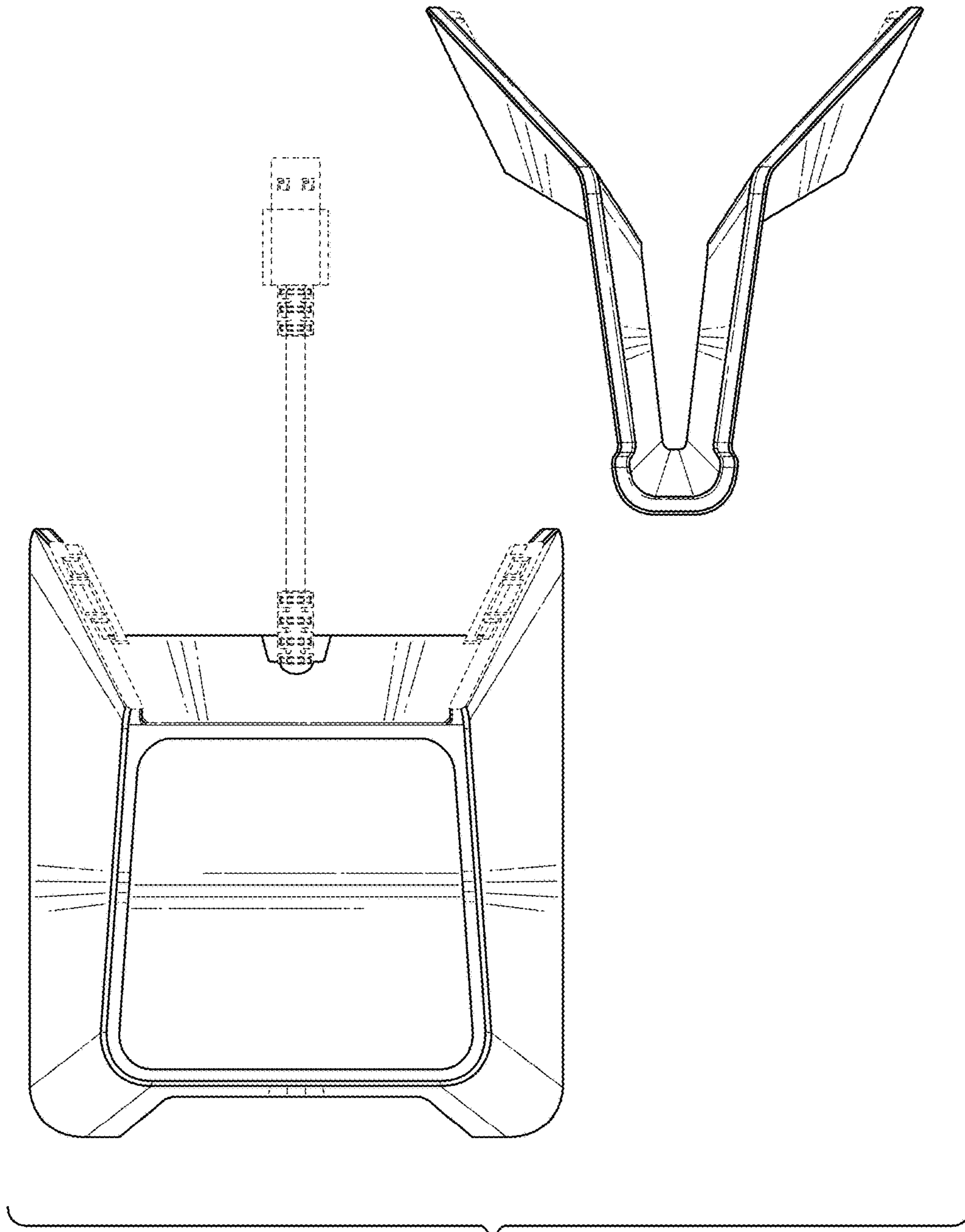


FIG. 24

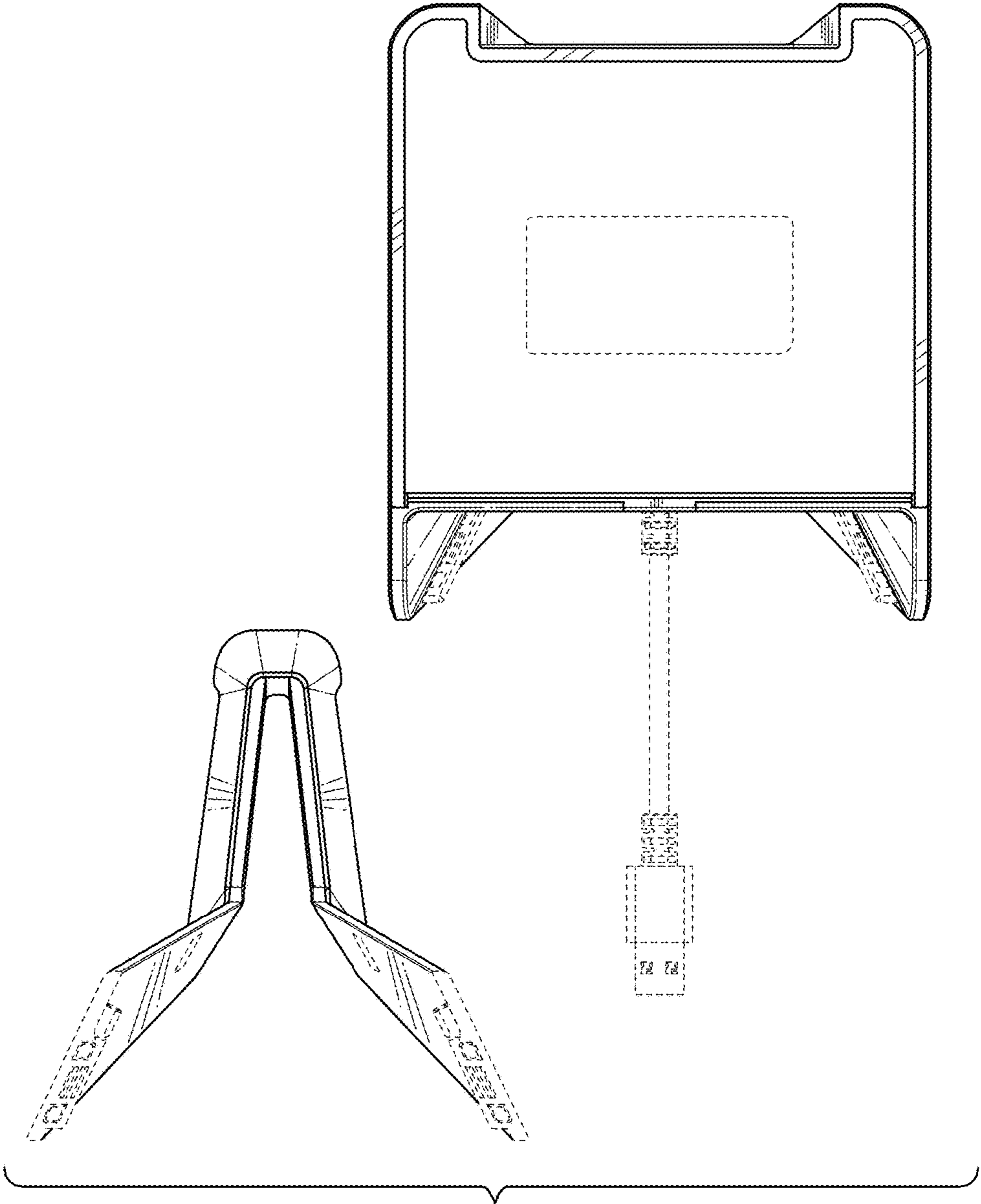


FIG. 25

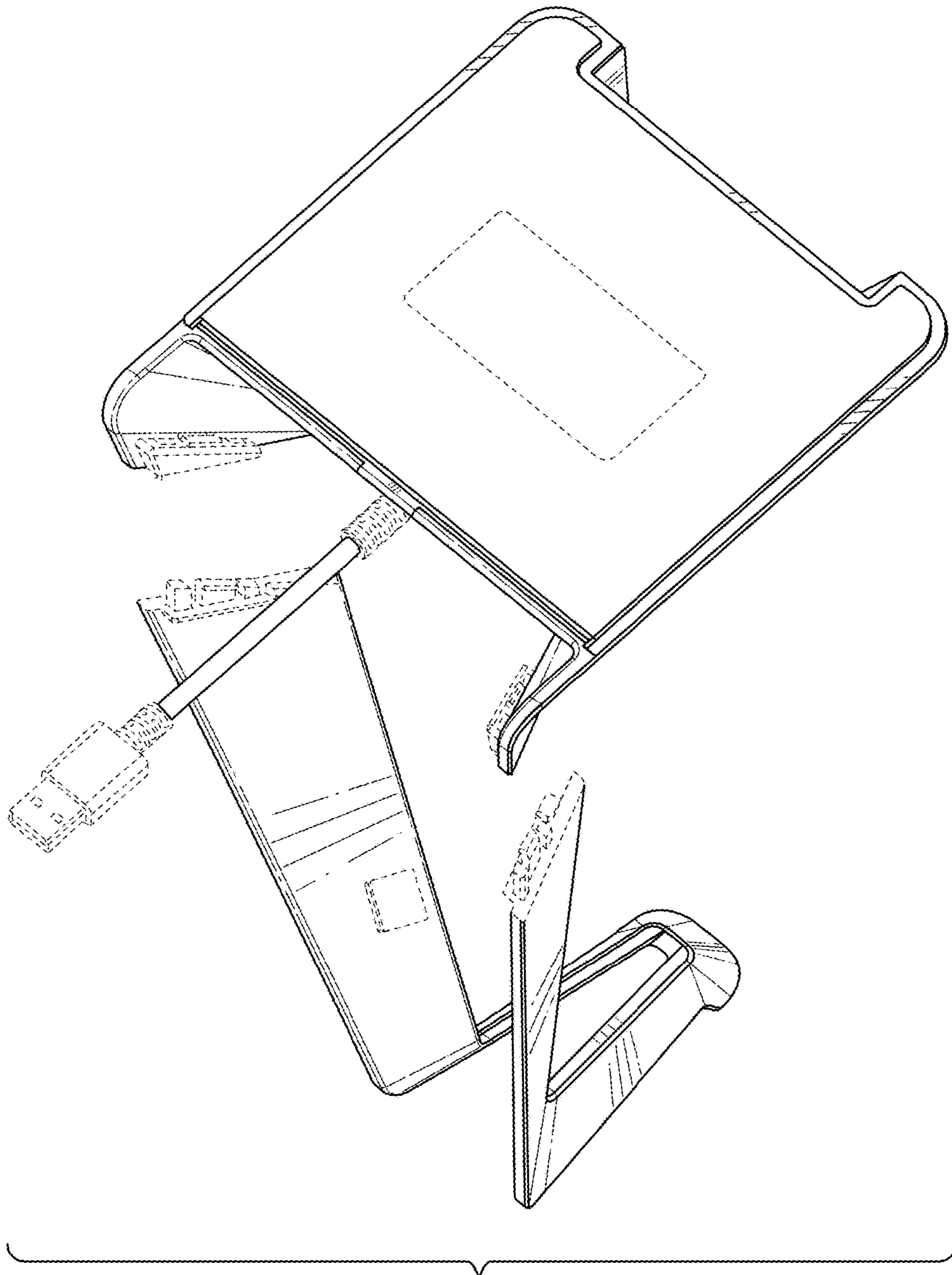


FIG. 26